

The listing of claims will replace all prior versions and listing of claims in the application:

Listing of Claims:

Cancel Claim 1.

Claim 2.(amended) The substrate curable unreinforced resin composition of claim 33 4, wherein said poly(arylene ether) polyvinyl resin has an number average molecular weight of less than about 10,000 g/mol.

Claim 3.(amended) The substrate curable unreinforced resin composition of claim 2, wherein said poly(arylene ether) polyvinyl resin has a number average molecular weight of less than about 5,000 g/mol.

Claim 4.(amended) The substrate curable unreinforced resin composition of claim 33 4, wherein said poly(arylene ether) polyvinyl resin has an number average molecular weight of between about 20,000 and 75,000 g/mol.

Claim 5.(amended) The substrate curable unreinforced resin composition of claim 4, wherein said poly(arylene ether) polyvinyl resin has an number average molecular weight between about 30,000 to about 71,000.

Claim 6.(amended) The substrate curable unreinforced resin composition of claim 4, which additionally comprises a catalyst.

Claim 7.(amended) The substrate curable unreinforced resin composition of claim 4, which additionally comprises a complementary, non-reactive material being one or more of a thermoset resin, a thermoplastic resin, or an elastomeric resin.

Claim 8.(amended) The substrate curable unreinforced resin composition of claim 7, wherein said complementary, non-reactive material is one or more of nylon, polystyrene, or polypropylene.

Claim 9.(amended) The substrate curable unreinforced resin composition of claim 7, wherein said complementary, non-reactive material is one or more of nylon, polystyrene, or polypropylene.

Claim 10.(amended) The ~~substrate curable unreinforced resin composition~~ of claim 33 4, which further comprises one or more of catalysts, flame-retardants, organic solvents, and curing agents.

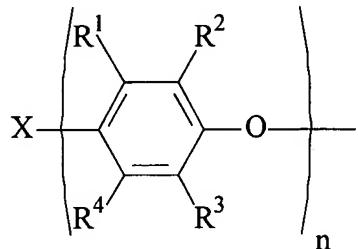
Claim 11.(amended) The ~~substrate curable unreinforced resin composition~~ of claim 33 4, wherein said poly(arylene ether) polyvinyl resin has an average molecular weight of between about 900 and 10,000.

Claim 12.(amended) The ~~substrate curable unreinforced resin composition~~ of claim 33 4, wherein said poly(arylene ether) comprises poly(phenylene ether) compounds of general structure, 1:

$Q-(J-K)_y$

1

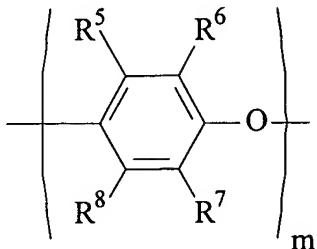
wherein Q is the residuum of a phenol and comprises radicals of the following structure, 2:



2

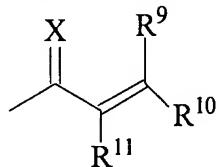
wherein, for structure 2, X is hydrogen, substituted or unsubstituted C₁₋₁₀₀ alkyl, aryl, and mixed alkyl-aryl hydrocarbons, or such hydrocarbon groups containing a substituent selected from the group consisting of carboxylic acid, halogen, aldehyde, alcohol, and amino radicals; X may be sulfur, sulfonyl, sulfuryl, oxygen, or other such bridging group having a valency of 2 to result in bis- or higher polyphenols; R¹⁻⁴ independently may be hydrogen, substituted or unsubstituted C₁₋₁₀₀ alkyl, alkenyl, alkynoyl, aryl, mixed alkyl-aryl hydrocarbons, or such groups also containing a substituent selected from the group

consisting of carboxylic acid, aldehyde, alcohol, halogen, and amino functionality; y and n independently range from about 1-100; and J comprises recurring units of the following structure, 3:



3

wherein, for structure 3, R⁵⁻⁸ independently may be hydrogen, alkyl, alkenyl, alkynoyl, aryl, mixed alkyl-aryl hydrocarbons, or such groups also containing a substituent selected from the group consisting of carboxylic acid, aldehyde, alcohol, and amino functionality, and m ranges from 1-200; and K has the following structure:



wherein X is O, S, or two hydrogens, and wherein R⁹⁻¹¹ are independently a hydrogen or substituted or unsubstituted C₁₋₁₀₀ alkyl or aryl or mixed alkyl or aryl group, wherein any of the foregoing "R" substituents optionally may be partially or fully halogenated, and wherein, any one of the R⁵⁻⁸ substituents also may be used for the R¹⁻⁴ groups.

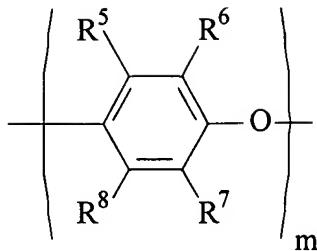
Claim 13.(amended) The ~~substrate curable unreinforced resin composition~~ of claim 12, wherein said poly(phenylene ether) (PPE) comprises those of the general structure, 1:

Q-(J-K)_m

1

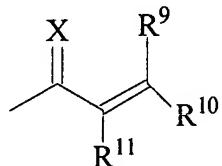
wherein Q is the residuum of a phenol;

J comprises recurring units of the following structure, 3:



3

wherein, for structure 3, R⁵⁻⁸ independently is selected from hydrogen, alkyl, alkenyl, alkynoyl, aryl, mixed alkyl-aryl hydrocarbons, wherein such groups may contain a substituent selected from carboxylic acid, aldehyde, alcohol, and amino functionality; K has the following structure:



wherein R⁹⁻¹¹ is a hydrogen or substituted or unsubstituted C₁₋₁₀₀ alkyl or aryl or mixed alkyl or aryl group; X is an oxygen, and m ranges from 1-200.

Cancel Claims 14-32.

Claim 33.(amended) A substrate coated with an adhesive layer of the curable unreinforced composition, which comprises: of claim 1

- (a) at least one poly(arylene ether) polyvinyl resin having a number molecular weight of between about 900 and 75,000; and
- (b) at least one vinyl or acrylic-substituted resin.

Cancel Claims 34- 35.

Claim 36.(original) The substrate of claim 33, which is an electrically conductive metal.

Claim 37.(original) The substrate of claim 36, wherein said conductive metal is copper.

Claim 38.(original) The substrate of claim 36, which is flexible.

Cancel Claims 39-41.

Claim 42.(amended) A flexible article, comprising two flexible substrates laminated together with said curable composition of claim 33 4.

Cancel Claims 43-73.

74. (new) The substrate of claim 33, wherein said poly(arylene ether) polyvinyl resin has an iodine value (IV) of around 0.31.